

## Product Change Notification

(Notification – P2212070-DI)

(PA220009)

December 1, 2022

**To:** *Our Valued Distribution Customer*

**Overview:** The purpose of this notification is to communicate a change to Renesas Electronics America, Inc. (REA) devices.

This notification announces an update to the standard interior labels for all shipments. See the Appendix for additional details.

There is no impact to part numbers, specifications, fit, form, characteristics, quality & reliability of the products.

**Affected Products:** All Renesas Devices

**Key Dates:**

Shipments using new labels for Legacy Intersil (REN-PWR), Legacy IDT (REN-ANLG) & Legacy Dialog (REN-DIA) product begins. Cross shipment of products with old and new labels may occur for a period of time.	Aug. 1, 2023
Shipments using new labels for Legacy Renesas (REN-EP) product begins. Cross shipment of products with old and new labels may occur for a period of time.	Apr. 1, 2024

**Response:** No response is required.

Questions or requests pertaining to this notice, including additional data, must be sent to Renesas within 30 days.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

## Appendix A: Legacy Intersil (REN-PWR) Products

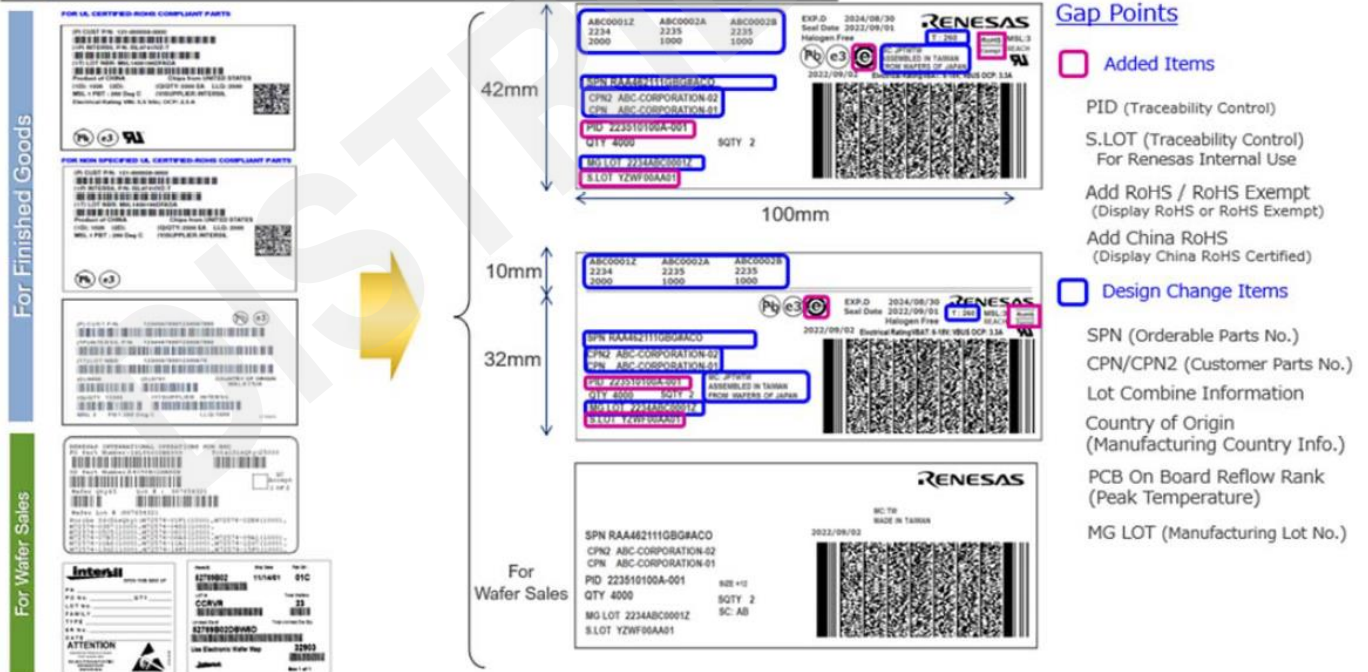
Effective Date: August 1, 2023

Table: Label Display Item

Label Display Item
1 Lot Combine Information
2 D/N (Device Name)
3 SPN (SAP Parts Name)
4 CPN / CPN2 (Customer Parts No.)
5 PID (Pack ID)
6 QTY
7 MG LOT (Manufacturing Lot No.)
8 S.Lot (Shipping Batch Lot)
9 SQTY (Wafers Q'ty)
10 OSAT Code
11 Expiry Date
12 Seal Date
13 Halogen Free
14 Pb-Free Logo Mark
15 Pb-Free with Detail Rank Information
16 China RoHS (Logo Mark or "Blank")
17 Country of Origin
18 PCB On Board Reflow Rank (Peak Temp)
19 Labeling Date
20 Condition after opening (MSL Rank)
21 RoHS Exempt (RoHS or RoHS Exempt)
22 REACH Certified (REACH or "Blank")
23 UL Certified
24 UL Rank
25 Wafer Size
26 Partial Lot Sign
27 Mix Lot Sign



## Gap Points Current and New / Ex-ISL



## Appendix B: Legacy IDT (REN-ANALOG) Products

Effective Date: August 1, 2023

Table: Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



## Gap Points Current and New / Ex-IDT

**For Finished Goods**

**For Wafer Sales**

42mm

100mm

10mm

32mm

For Wafer Sales

**Gap Points**

- Added Items
  - PID (Traceability Control)
  - S.LOT (Traceability Control) For Renesas Internal Use
- Design Change Items
  - SPN (Orderable Parts No.)
  - Lot Combine Information
  - MG LOT (Manufacturing Lot No.)
  - Pb-Free's Logo Mark
  - Country of Origin (Manufacturing Country Info.)
  - PCB On Board Reflow Rank (Peak Temperature)

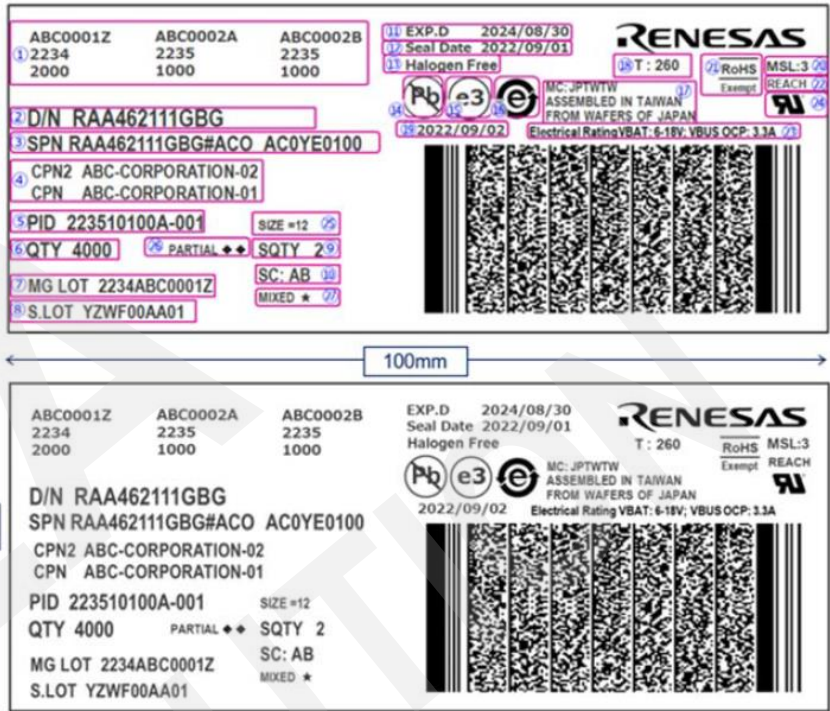


### Appendix C: Legacy Dialog (REN-DIALOG) Products

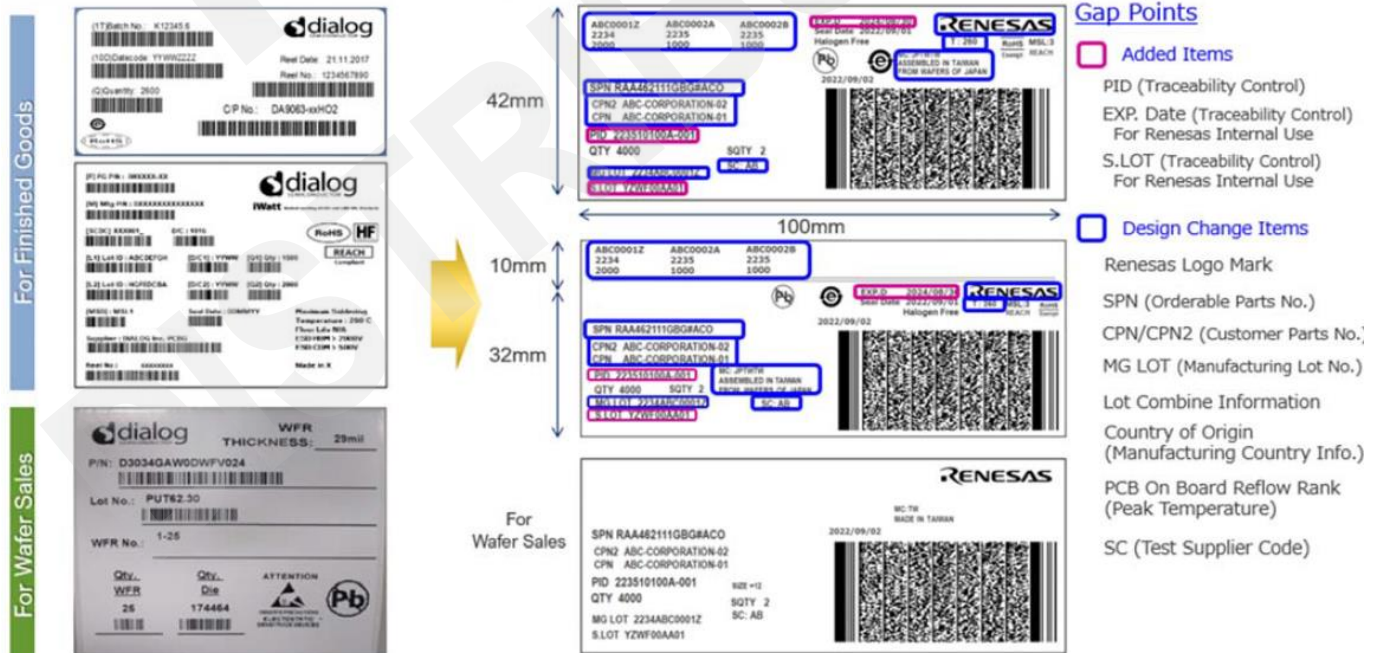
Effective Date: August 1, 2023

Table: Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



### Gap Points Current and New / Ex-DLG



## Appendix D: Legacy Renesas (REN-EP) Products

Effective Date: April 1, 2024

Table: Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



## Gap Points Current and New / Renesas Japan (REL)



### Gap Points

- Design Change Items
- Pb-Free's Logo Mark
- PCB On Board Reflow Rank (Peak Temperature)
- Customer Parts No. (Display Name Change) PN/PN2 => CPN/CPN2
- MG LOT (Display Name Change) T/C => MG LOT
- PCN (Deleted Item)